Last Updated: Dec. 2007

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### **GRAPHICS MEMORY PART NUMBERING**

# <u>H 5 X X XX X X X X X X - XX X</u> 1 2 3 4 5 6 7 8 9 10 11 1213 14

## HYNIX MEMORY

#### **PRODUCT FAMILY**

5 : DRAM

#### **PRODUCT MODE**

D : DDR SDRAM
P : DDR2 SDRAM
T : DDR3 SDRAM
R : GDDR3 SDRAM
F : GDDR4 SDRAM
G : GDDR5 SDRAM

#### **POWER SUPPLY CODE**

V : VDD =3.3V & VDDQ = 3.3V A : VDD =3.3V & VDDQ = 2.5V Y : VDD =3.0V & VDDQ = 3.0V U : VDD =2.5V & VDDQ = 2.5V W : VDD =2.5V & VDDQ = 1.8V S : VDD =1.8V & VDDQ = 1.8V Q : VDD =1.5V & VDDQ = 1.5V R : VDD =1.2V & VDDQ = 1.2V

#### **DENSITY & REFRESH CODE**

16 : 16M / 4K REF / 64ms 32 : 32M / 4K REF / 64ms : 64M / 4K REF / 64ms 12 : 128M / 4K REF / 64ms 25 : 256M / 8K REF / 64ms 26 : 256M / 4K REF / 64ms 27 : 256M / 4K REF / 32ms 51 : 512M / 8K REF / 64ms 52 : 512M / 8K REF / 32ms 53 : 512M / 4K REF / 64ms : 1G / 8K REF / 64ms 1H : 1G / 8K REF / 32ms 2G : 2G / 8K REF / 64ms 4G : 4G / 8K REF / 64ms

#### **ORGANIZATION CODE**

6 : x16 2 : x32 A : x64

#### **NUMBER of BANKS**

1 : 2Banks
2 : 4Banks
3 : 8Banks
4 : 16Banks
5 : 32Banks

Note. 1) Extended Temperature:  $-25^{\circ}$ C  $\sim 85^{\circ}$ C

2) Industrial Temperature: -40°C ~ 85°C

3) ROHS (Restriction Of Hazardous Substances) compliant

# OPERATION TEMPERATURE & POWER CONSUMPTION

 $\label{eq:commercial} \begin{array}{ll} \text{C : } & \text{Commercial Temp \& Normal Power} \\ \text{E : Extended Temp}^{1)} & \text{Normal Power} \end{array}$ 

I : Industrial Temp<sup>2)</sup> & Normal Power L : Commercial Temp & Low Power

G: Extended Temp<sup>1)</sup> & Low Power

J: Industrial Temp<sup>2)</sup> & Low Power

#### **SPEED**

N7: 1.75Ghz 18:550Mhz 60:166Mhz 55:183Mhz 16:600Mhz N8: 1.8Ghz 14:700Mhz T0: 2.0Ghz 50: 200Mhz 12:800Mhz T1: 2.25Ghz 43: 233Mhz 11:900Mhz T2: 2.5Ghz 40: 250Mhz N0: 1.0Ghz T3: 2.75Ghz 36: 275Mhz N1: 1.1Ghz R0: 3.0Ghz 33:300Mhz

28 : 350Mhz N2 : 1.2Ghz 26 : 385Mhz N3 : 1.3Ghz 25 : 400Mhz N4 : 1.4Ghz 22 : 450Mhz N5 : 1.5Ghz 20 : 500Mhz N6 : 1.6Ghz

#### PACKAGE MATERIAL

L: Leaded

P: Lead free(ROHS<sup>3)</sup> Compliant) R: Lead & Halogen free

(ROHS<sup>3)</sup> Compliant)

#### PACKAGE TYPE

T : TSOP II

F: FBGA (Wire Bond)

M : FBGA / DDP (Dual Die PKG)H : FBGA / QDP (Quad Die PKG)

J : FBGA (Flip Chip)

#### **DIE GENERATION**

M: 1st Gen. D: 5th Gen. A: 2nd Gen. E: 6th Gen. B: 3rd Gen. F: 7th Gen. C: 4th Gen. G: 8th Gen.